

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,060,620 B2
APPLICATION NO. : 10/671812
DATED : June 13, 2006
INVENTOR(S) : Richtarch

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 6:

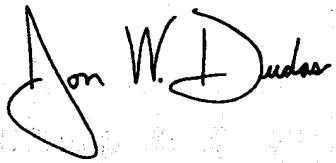
Line 12, after "The method of claim 1" insert -- wherein --.

Line 51, after "polishing the conditioned SiC" delete "surthee" and insert -- surface --.

Line 53, after "provide a wafer surface" delete "tax" and insert -- that --.

Signed and Sealed this

Fifteenth Day of August, 2006



JON W. DUDAS
Director of the United States Patent and Trademark Office